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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	416
Number of Logic Elements/Cells	4160
Total RAM Bits	53248
Number of I/O	93
Number of Gates	263000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k100cf144c9

…and More Features

- Low-power operation design
  - 1.8-V supply voltage (see Table 2)
  - Copper interconnect reduces power consumption
  - MultiVolt™ I/O support for 1.8-V, 2.5-V, and 3.3-V interfaces
  - ESBs offering programmable power-saving mode
- Flexible clock management circuitry with up to four phase-locked loops (PLLs)
  - Built-in low-skew clock tree
  - Up to eight global clock signals
  - ClockLock™ feature reducing clock delay and skew
  - ClockBoost™ feature providing clock multiplication and division
  - ClockShift™ feature providing programmable clock phase and delay shifting
- Powerful I/O features
  - Compliant with peripheral component interconnect Special Interest Group (PCI SIG) ***PCI Local Bus Specification, Revision 2.2*** for 3.3-V operation at 33 or 66 MHz and 32 or 64 bits
  - Support for high-speed external memories, including DDR synchronous dynamic RAM (SDRAM) and ZBT static RAM (SRAM)
  - 16 input and 16 output LVDS channels
  - Direct connection from I/O pins to local interconnect providing fast t_{CO} and t_{SU} times for complex logic
  - MultiVolt I/O support for 1.8-V, 2.5-V, and 3.3-V interfaces
  - Programmable clamp to V_{CCIO}
  - Individual tri-state output enable control for each pin
  - Programmable output slew-rate control to reduce switching noise
  - Support for advanced I/O standards, including low-voltage differential signaling (LVDS), LVPECL, PCI-X, AGP, CTT, SSTL-3 and SSTL-2, GTL+, and HSTL Class I
  - Supports hot-socketing operation
  - Pull-up on I/O pins before and during configuration

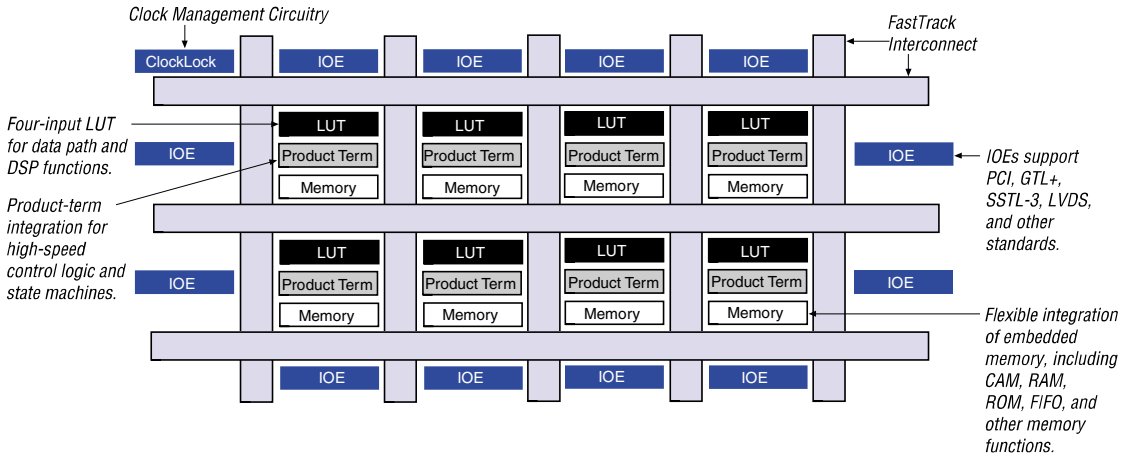
Table 2. APEX 20KC Supply Voltages

Feature	Voltage
Internal supply voltage (V_{CCINT})	1.8 V
MultiVolt I/O interface voltage levels (V_{CCIO})	1.8 V, 2.5 V, 3.3 V, 5.0 V *(1)*

Note:
(1) APEX 20KC devices can be 5.0-V tolerant by using an external resistor.

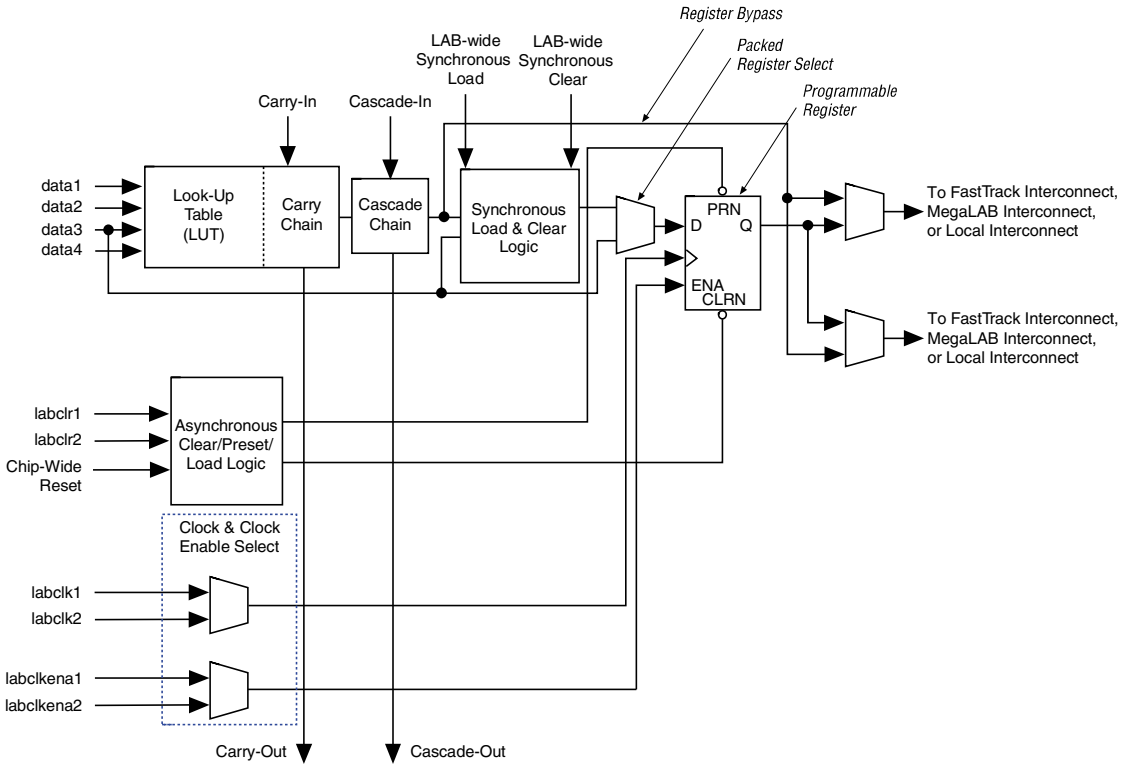
The ESB can implement a variety of memory functions, including CAM, RAM, dual-port RAM, ROM, and FIFO functions. Embedding the memory directly into the die improves performance and reduces die area compared to distributed-RAM implementations. Moreover, the abundance of cascadable ESBs allows APEX 20KC devices to implement multiple wide memory blocks for high-density designs. The ESB's high speed ensures it can implement small memory blocks without any speed penalty. Additionally, designers can use the ESBs to create as many different-sized memory blocks as the system requires. Figure 1 shows an overview of the APEX 20KC device.

Figure 1. APEX 20KC Device Block Diagram



APEX 20KC devices provide four dedicated clock pins and four dedicated input pins that drive register control inputs. These signals ensure efficient distribution of high-speed, low-skew control signals, which use dedicated routing channels to provide short delays and low skews. Four of the dedicated inputs drive four global signals. These four global signals can also be driven by internal logic, providing an ideal solution for a clock divider or internally generated asynchronous clear signals with high fan-out. The dedicated clock pins featured on the APEX 20KC devices can also feed logic. The devices also feature ClockLock and ClockBoost clock management circuitry.

Figure 5. APEX 20KC Logic Element



Each LE's programmable register can be configured for D, T, JK, or SR operation. The register's clock and clear control signals can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinatorial functions, the register is bypassed and the output of the LUT drives the outputs of the LE.

Each LE has two outputs that drive the local, MegaLAB, or FastTrack interconnect routing structure. Each output can be driven independently by the LUT's or register's output. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, improves device utilization because the register and the LUT can be used for unrelated functions. The LE can also drive out registered and unregistered versions of the LUT output.

The APEX 20KC architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. A carry chain supports high-speed arithmetic functions such as counters and adders, while a cascade chain implements wide-input functions such as equality comparators with minimum delay. Carry and cascade chains connect LEs 1 through 10 in an LAB and all LABs in the same MegaLAB structure.

Carry Chain

The carry chain provides a very fast carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higher-order bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the APEX 20KC architecture to implement high-speed counters, adders, and comparators of arbitrary width. Carry chain logic can be created automatically by the Quartus II Compiler during design processing, or manually by the designer during design entry. Parameterized functions such as DesignWare functions from Synopsys and library of parameterized modules (LPM) functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than ten LEs by automatically linking LABs together. For enhanced fitting, a long carry chain skips alternate LABs in a MegaLAB structure. A carry chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure.

Figure 6 shows how an *n*-bit full adder can be implemented in *n* + 1 LEs with the carry chain. One portion of the LUT generates the sum of two bits using the input signals and the carry-in signal; the sum is routed to the output of the LE. The register can be bypassed for simple adders or used for accumulator functions. Another portion of the LUT and the carry chain logic generates the carry-out signal, which is routed directly to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is driven onto the local, MegaLAB, or FastTrack interconnect routing structures.

The counter mode uses two 3-input LUTs: one generates the counter data, and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading, and another AND gate provides synchronous clearing. If the cascade function is used by an LE in counter mode, the synchronous clear or load overrides any signal carried on the cascade chain. The synchronous clear overrides the synchronous load. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

Clear & Preset Logic Control

Logic for the register's clear and preset signals is controlled by LAB-wide signals. The LE directly supports an asynchronous clear function. The Quartus II Compiler can use a NOT-gate push-back technique to emulate an asynchronous preset or to emulate simultaneous preset and clear or asynchronous load. However, this technique uses three additional LEs per register. All emulation is performed automatically when the design is compiled. Registers that emulate simultaneous preset and load will enter an unknown state upon power-up or when the chip-wide reset is asserted.

In addition to the two clear and preset modes, APEX 20KC devices provide a chip-wide reset pin (DEV_CLRn) that resets all registers in the device. Use of this pin is controlled through an option in the Quartus II software that is set before compilation. The chip-wide reset overrides all other control signals. Registers using an asynchronous preset are preset when the chip-wide reset is asserted; this effect results from the inversion technique used to implement the asynchronous preset.

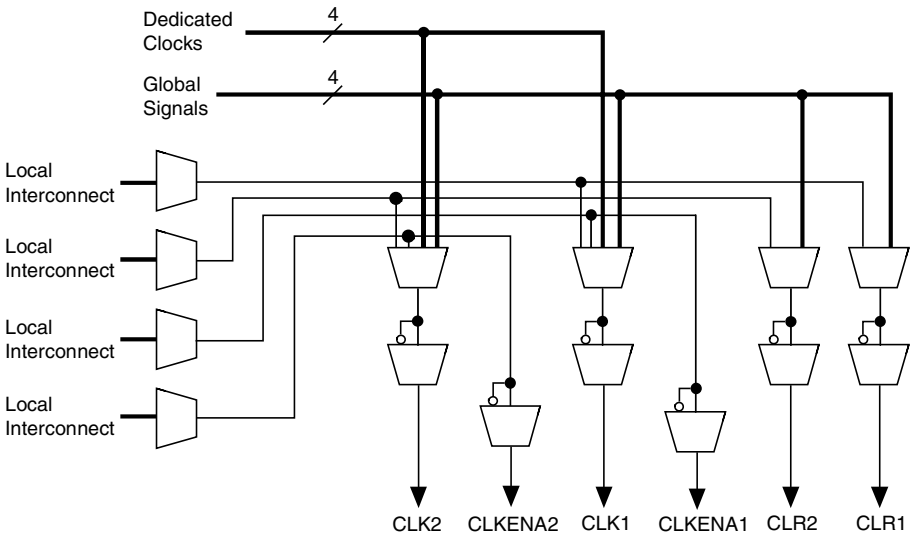
FastTrack Interconnect

In the APEX 20KC architecture, connections between LEs, ESBs, and I/O pins are provided by the FastTrack interconnect. The FastTrack interconnect is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack interconnect consists of row and column interconnect channels that span the entire device. The row interconnect routes signals throughout a row of MegaLAB structures; the column interconnect routes signals throughout a column of MegaLAB structures. When using the row and column interconnect, an LE, IOE, or ESB can drive any other LE, IOE, or ESB in a device. See Figure 9.

The programmable register also supports an asynchronous clear function. Within the ESB, two asynchronous clears are generated from global signals and the local interconnect. Each macrocell can either choose between the two asynchronous clear signals or choose to not be cleared. Either of the two clear signals can be inverted within the ESB. Figure 15 shows the ESB control logic when implementing product-terms.

Figure 15. ESB Product-Term Mode Control Logic



Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 32 product terms to feed the macrocell OR logic directly, with two product terms provided by the macrocell and 30 parallel expanders provided by the neighboring macrocells in the ESB.

The Quartus II Compiler can allocate up to 15 sets of up to two parallel expanders per set to the macrocells automatically. Each set of two parallel expanders incurs a small, incremental timing delay. Figure 16 shows the APEX 20KC parallel expanders.

ESBs can implement synchronous RAM, which is easier to use than asynchronous RAM. A circuit using asynchronous RAM must generate the RAM write enable (WE) signal, while ensuring that its data and address signals meet setup and hold time specifications relative to the WE signal. In contrast, the ESB's synchronous RAM generates its own WE signal and is self-timed with respect to the global clock. Circuits using the ESB's self-timed RAM must only meet the setup and hold time specifications of the global clock.

ESB inputs are driven by the adjacent local interconnect, which in turn can be driven by the FastTrack or MegaLAB interconnect. Because the ESB can be driven by the local interconnect, an adjacent LE can drive it directly for fast memory access. ESB outputs drive the FastTrack and MegaLAB interconnects. In addition, ten ESB outputs, nine of which are unique output lines, drive the local interconnect for fast connection to adjacent LEs or for fast feedback product-term logic.

When implementing memory, each ESB can be configured in any of the following sizes: 128 × 16, 256 × 8, 512 × 4, 1,024 × 2, or 2,048 × 1. By combining multiple ESBs, the Quartus II software implements larger memory blocks automatically. For example, two 128 × 16 RAM blocks can be combined to form a 128 × 32 RAM block, and two 512 × 4 RAM blocks can be combined to form a 512 × 8 RAM block. Memory performance does not degrade for memory blocks up to 2,048 words deep. Each ESB can implement a 2,048-word-deep memory; the ESBs are used in parallel, eliminating the need for any external control logic and its associated delays.

To create a high-speed memory block that is more than 2,048 words deep, ESBs drive tri-state lines. Each tri-state line connects all ESBs in a column of MegaLAB structures, and drives the MegaLAB interconnect and row and column FastTrack interconnect throughout the column. Each ESB incorporates a programmable decoder to activate the tri-state driver appropriately. For instance, to implement 8,192-word-deep memory, four ESBs are used. Eleven address lines drive the ESB memory, and two more drive the tri-state decoder. Depending on which 2,048-word memory page is selected, the appropriate ESB driver is turned on, driving the output to the tri-state line. The Quartus II software automatically combines ESBs with tri-state lines to form deeper memory blocks. The internal tri-state control logic is designed to avoid internal contention and floating lines. See Figure 18.

Advanced I/O Standard Support

APEX 20KC IOEs support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.

For more information on I/O standards supported by APEX 20KC devices, see *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

The APEX 20KC device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own `VCCIO` pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K400C and larger APEX 20KC devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K400C and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400C devices and larger add a serializer/deserializer circuit and PLL for support up to 840 Mbit per channel.

Each bank can support multiple standards with the same `VCCIO` for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same `VCCIO` voltage level. For example, when `VCCIO` is 3.3 V, a bank can support LVTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used for the LVDS I/O standard, they support all of the other I/O standards. Figure 28 shows the arrangement of the APEX 20KC I/O banks.

Signals can be driven into APEX 20KC devices before and during power-up without damaging the device. In addition, APEX 20KC devices do not drive out during power-up. Once operating conditions are reached and the device is configured, APEX 20KC devices operate as specified by the user.

MultiVolt I/O Interface

The APEX architecture supports the MultiVolt I/O interface feature, which allows APEX devices in all packages to interface with systems of different supply voltages. The devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

APEX 20KC devices support the MultiVolt I/O interface feature. The APEX 20KC VCCINT pins must always be connected to a 1.8-V power supply. With a 1.8-V V_{CCINT} level, input pins are 1.8-V, 2.5-V, and 3.3-V tolerant. The VCCIO pins can be connected to either a 1.8-V, 2.5-V, or 3.3-V power supply, depending on the I/O standard requirements. When the VCCIO pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and compatible with 3.3-V or 5.0-V systems. An APEX 20KC device is 5.0-V tolerant with the addition of a resistor.

Table 10 summarizes APEX 20KC MultiVolt I/O support.

Table 10. APEX 20KC MultiVolt I/O Support

V_{CCIO} (V)	Input Signals (V)				Output Signals (V)			
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0
1.8	✓	✓ (1)	✓ (1)		✓			
2.5		✓	✓ (1)			✓		
3.3		✓	✓	✓ (2)		✓ (3)	✓	✓

Notes:
(1) The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}, except for the 5.0-V input case.
(2) An APEX 20KC device can be made 5.0-V tolerant with the addition of an external resistor.
(3) When V_{CCIO} = 3.3 V, an APEX 20KC device can drive a 2.5-V device with 3.3-V tolerant inputs.

Open-drain output pins on APEX 20KC devices (with a series resistor and a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a V_{IH} of 3.5 V. When the pin is inactive, the trace will be pulled up to 5.0 V by the resistor. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor.

ClockLock & ClockBoost Features

APEX 20KC devices support the ClockLock and ClockBoost clock management features, which are implemented with PLLs. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost circuitry allows the designer to distribute a low-speed clock and multiply that clock on-device. APEX 20KC devices include a high-speed clock tree; unlike ASICs, the user does not have to design and optimize the clock tree. The ClockLock and ClockBoost features work in conjunction with the APEX 20KC device's high-speed clock to provide significant improvements in system performance and bandwidth. APEX 20KC devices in -7 and -8 speed grades include the ClockLock feature.

The ClockLock and ClockBoost features in APEX 20KC devices are enabled through the Quartus II software. External devices are not required to use these features.

APEX 20KC ClockLock Feature

APEX 20KC devices include up to four PLLs, which can be used independently. Two PLLs are designed for either general-purpose use or LVDS use (on devices that support LVDS I/O pins). The remaining two PLLs are designed for general-purpose use. The EP20K100C and EP20K200C devices have two PLLs; the EP20K400C and larger devices have four PLLs.

The following sections describe some of the features offered by the APEX 20KC PLLs.

External PLL Feedback

The ClockLock circuit's output can be driven off-chip to clock other devices in the system; further, the feedback loop of the PLL can be routed off-chip. This feature allows the designer to exercise fine control over the I/O interface between the APEX 20KC device and another high-speed device, such as SDRAM.

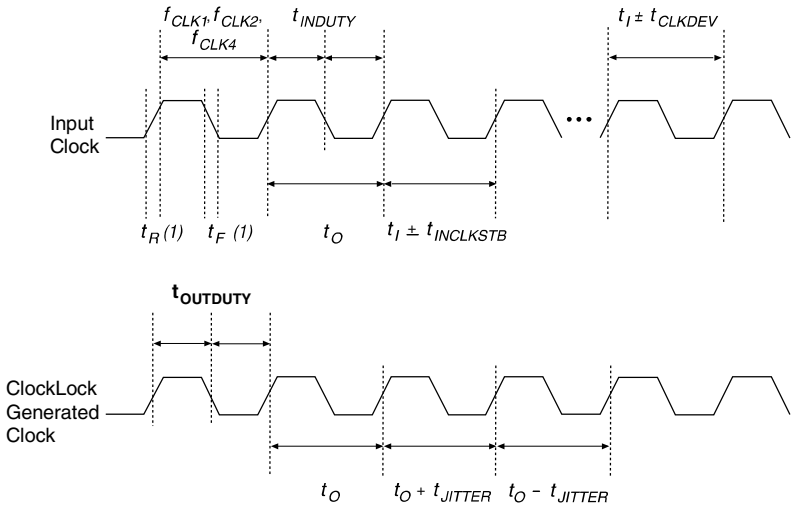
ClockLock & ClockBoost Timing Parameters

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the APEX 20KC ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. In APEX 20KC devices, the clock input standard is programmable, so the PLL cannot respond to the clock until the device is configured. The PLL locks onto the input clock as soon as configuration is complete. Figure 29 shows the incoming and generated clock specifications.

For more information on ClockLock and ClockBoost circuitry, see *Application Note 115: Using the ClockLock and ClockBoost PLL Features in APEX Devices*.

Figure 29. Specifications for the Incoming & Generated Clocks

The t_I parameter refers to the nominal input clock period; the t_O parameter refers to the nominal output clock period.



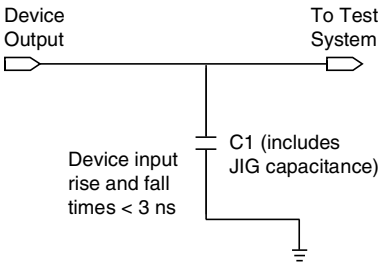
Note:
(1) Rise and fall times are measured from 10% to 90%.

Generic Testing

Each APEX 20KC device is functionally tested. Complete testing of each configurable SRAM bit and all logic functionality ensures 100% yield. AC test measurements for APEX 20KC devices are made under conditions equivalent to those shown in Figure 31. Multiple test patterns can be used to configure devices during all stages of the production flow. AC test criteria include:

- Power supply transients can affect ACmeasurements.
- Simultaneous transitions of multiple outputs should be avoided for accurate measurement.
- Threshold tests must not be performed under AC conditions.
- Large-amplitude, fast-ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result.

Figure 31. APEX 20KC AC Test Conditions



Operating Conditions

Tables 17 through 20 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for 1.8-V APEX 20KC devices.

Table 17. APEX 20KC Device Absolute Maximum Ratings *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage	With respect to ground *(2)*	–0.5	2.5	V
V_{CCIO}			–0.5	4.6	V
V_I	DC input voltage		–0.5	4.6	V
I_{OUT}	DC output current, per pin		–25	25	mA
T_{STG}	Storage temperature	No bias	–65	150	° C
T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	PQFP, RQFP, TQFP, and BGA packages, under bias		135	° C
		Ceramic PGA packages, under bias		150	° C

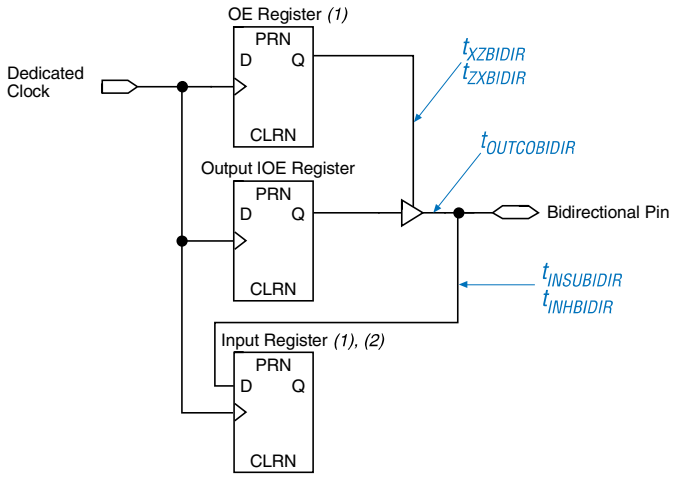
Table 30. SSTL-2 Class II Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{CCIO}	I/O supply voltage		2.375	2.5	2.625	V
V_{TT}	Termination voltage		V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04	V
V_{REF}	Reference voltage		1.15	1.25	1.35	V
V_{IH}	High-level input voltage		V_{REF} + 0.18		V_{CCIO} + 0.3	V
V_{IL}	Low-level input voltage		–0.3		V_{REF} – 0.18	V
V_{OH}	High-level output voltage	I_{OH} = –15.2 mA *(1)*	V_{TT} + 0.76			V
V_{OL}	Low-level output voltage	I_{OL} = 15.2 mA *(2)*			V_{TT} – 0.76	V

Table 31. SSTL-3 Class I Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{CCIO}	I/O supply voltage		3.0	3.3	3.6	V
V_{TT}	Termination voltage		V_{REF} – 0.05	V_{REF}	V_{REF} + 0.05	V
V_{REF}	Reference voltage		1.3	1.5	1.7	V
V_{IH}	High-level input voltage		V_{REF} + 0.2		V_{CCIO} + 0.3	V
V_{IL}	Low-level input voltage		–0.3		V_{REF} – 0.2	V
V_{OH}	High-level output voltage	I_{OH} = –8 mA *(1)*	V_{TT} + 0.6			V
V_{OL}	Low-level output voltage	I_{OL} = 8 mA *(2)*			V_{TT} – 0.6	V

Figure 34. Synchronous Bidirectional Pin External Timing



Notes:

(1) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin. Use the "Output Enable Routing = Single-Pin" option in the Quartus II software to set the output enable register.

(2) Use the "Decrease Input Delay to Internal Cells = OFF" option in the Quartus II software to set the LAB-adjacent input register. This maintains a zero hold time for LAB-adjacent registers while giving a fast, position-independent setup time. Set "Decrease Input Delay to Internal Cells = ON" and move the input register farther away from the bidirectional pin for a faster setup time with zero hold time. The exact position where zero hold occurs with the minimum setup time varies with device density and speed grade.

Tables 37 to 39 describes the f_{MAX} timing parameters shown in Figure 33. Table 40 describes the functional timing parameters.

Table 37. APEX 20KC f_{MAX} LE Timing Parameters

Symbol	Parameter
t_{SU}	LE register setup time before clock
t_{H}	LE register hold time before clock
t_{CO}	LE register clock-to-output delay
t_{LUT}	LUT delay for data-in to data-out

Tables 43 through 78 show the f_{MAX} and external timing parameters for EPC20K100C, EPC20K200C, EP20K400C, EP20K600C, EP20K1000C, and EP20K1500C devices.

Table 43. EP20K100C f_{MAX} LE Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.3						ns
t_{H}	0.3						ns
t_{CO}		0.3					ns
t_{LUT}		0.7					ns

Table 44. EP20K100C f_{MAX} ESB Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.4					ns
t_{ESBSRC}		2.5					ns
t_{ESBAWC}		3.1					ns
t_{ESBSWC}		3.0					ns
$t_{ESBWASU}$	0.5						ns
t_{ESBWAH}	0.5						ns
$t_{ESBWDSU}$	0.6						ns
t_{ESBWDH}	0.5						ns
$t_{ESBRASU}$	1.4						ns
t_{ESBRAH}	0.0						ns
$t_{ESBWESU}$	2.3						ns
$t_{ESBDATASU}$	0.0						ns
$t_{ESBWADDRSU}$	0.2						ns
$t_{ESBRADDRSU}$	0.2						ns
$t_{ESBDATACO1}$		1.0					ns
$t_{ESBDATACO2}$		2.3					ns
t_{ESBDD}		2.7					ns
t_{PD}		1.6					ns
$t_{PTERMSU}$	1.0						ns
$t_{PTERMCO}$		1.0					ns

Table 52. EP20K200C Minimum Pulse Width Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade *(2)*		-9 Speed Grade *(2)*		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	2.2						ns
t_{CL}	2.3						ns
t_{CLRP}	0.2						ns
t_{PREP}	0.2						ns
t_{ESBCH}	2.3						ns
t_{ESBCL}	2.3						ns
t_{ESBWP}	1.1						ns
t_{ESBRP}	0.9						ns

Table 53. EP20K200C External Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade *(2)*		-9 Speed Grade *(2)*		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.0						ns
t_{INH}	0.0						ns
t_{OUTCO}	2.0	5.0					ns
$t_{INSUPLL}$	3.3						ns
t_{INHPLL}	0.0						ns
$t_{OUTCOPLL}$	0.5	2.1					ns

Table 54. EP20K200C External Bidirectional Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSUBIDIR}$	2.0						ns
$t_{INHBIDIR}$	0.0						ns
$t_{OUTCOBIDIR}$	2.0	5.0					ns
$t_{XZBIDIR}$		7.1					ns
$t_{ZXBIDIR}$		7.1					ns
$t_{INSUBIDIRPLL}$	3.9						ns
$t_{INHBIDIRPLL}$	0.0						ns
$t_{OUTCOBIDIRPLL}$	0.5	2.1					ns
$t_{XZBIDIRPLL}$		4.2					ns
$t_{ZXBIDIRPLL}$		4.2					ns

Table 55. EP20K400C f_{MAX} LE Timing Parameters Note (1)

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.3						ns
t_{H}	0.3						ns
t_{CO}		0.3					ns
t_{LUT}		0.6					ns

Table 58. EP20K400C Minimum Pulse Width Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade *(2)*		-9 Speed Grade *(2)*		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	2.0						ns
t_{CL}	2.0						ns
t_{CLRP}	0.2						ns
t_{PREP}	0.2						ns
t_{ESBCH}	2.0						ns
t_{ESBCL}	2.0						ns
t_{ESBWP}	1.0						ns
t_{ESBRP}	0.8						ns

Table 59. EP20K400C External Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade *(2)*		-9 Speed Grade *(2)*		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.1						ns
t_{INH}	0.0						ns
t_{OUTCO}	2.0	5.0					ns
$t_{INSUPLL}$	3.2						ns
t_{INHPLL}	0.0						ns
$t_{OUTCOPLL}$	0.5	2.1					ns

Table 66. EP20K600C External Bidirectional Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSUBIDIR}$	2.4						ns
$t_{INHBIDIR}$	0.0						ns
$t_{OUTCOBIDIR}$	2.0	5.0					ns
$t_{XZBIDIR}$		7.1					ns
$t_{ZXBIDIR}$		7.1					ns
$t_{INSUBIDIRPLL}$	3.9						ns
$t_{INHBIDIRPLL}$	0.0						ns
$t_{OUTCOBIDIRPLL}$	0.5	2.1					ns
$t_{XZBIDIRPLL}$		4.2					ns
$t_{ZXBIDIRPLL}$		4.2					ns

Table 67. EP20K1000C f_{MAX} LE Timing Parameters Note (1)

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.3						ns
t_{H}	0.3						ns
t_{CO}		0.3					ns
t_{LUT}		0.6					ns

Table 76. EP20K1500C Minimum Pulse Width Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade *(2)*		-9 Speed Grade *(2)*		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	2.0						ns
t_{CL}	2.0						ns
t_{CLRP}	0.2						ns
t_{PREP}	0.2						ns
t_{ESBCH}	2.0						ns
t_{ESBCL}	2.0						ns
t_{ESBWP}	1.0						ns
t_{ESBRP}	0.8						ns

Table 77. EP20K1500C External Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade *(2)*		-9 Speed Grade *(2)*		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.1						ns
t_{INH}	0.0						ns
t_{OUTCO}	2.0	5.0					ns
$t_{INSUPLL}$	3.2						ns
t_{INHPLL}	0.0						ns
$t_{OUTCOPLL}$	0.5	2.1					ns